

Title (en)
METHOD FOR PRODUCING A RELAY

Title (de)
VERFAHREN ZUR HERSTELLUNG EINES RELAIS

Title (fr)
PROCEDE DE PRODUCTION D'UN RELAIS

Publication
EP 1025573 B1 20020410 (DE)

Application
EP 98955329 A 19980915

Priority
• DE 9802729 W 19980915
• DE 19747166 A 19971024

Abstract (en)
[origin: WO9922392A1] A coil form (1) is injection moulded to form the base body of the relay. At least one fixed contact carrier (3,4), one contact-spring contact pin (5) and coil contact pins (9,10) embodied as wire sections in the form of drawn semi-finished products are introduced into the mould and extrusion-coated. The core (16) can also be embedded into the material of the coil form (1) if so desired. This dispenses with assembly processes involving the abrasion of plastic particles which can later become deposited on the contacts. All connector pieces can be mounted in a cost-effective manner in the injection mould, requiring as little material as possible by virtue of the fact that there is no wastage when the semi-finished wires are separated.

IPC 1-7
H01H 49/00; **H01H 50/04**; **H01H 50/14**

IPC 8 full level
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CPC (source: EP KR US)
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